



## AO4400

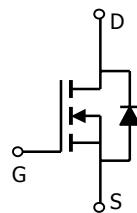
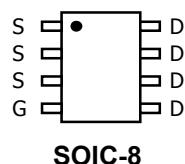
### N-Channel Enhancement Mode Field Effect Transistor

#### General Description

The AO4400 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications.

#### Features

$V_{DS}$  (V) = 30V  
 $I_D$  = 8.5A  
 $R_{DS(ON)} < 24m\Omega$  ( $V_{GS} = 10V$ )  
 $R_{DS(ON)} < 30m\Omega$  ( $V_{GS} = 4.5V$ )  
 $R_{DS(ON)} < 48m\Omega$  ( $V_{GS} = 2.5V$ )



#### Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Continuous Drain Current <sup>A</sup>	$I_D$	8.5	A
$T_A=70^\circ C$	$I_D$	7.1	
Pulsed Drain Current <sup>B</sup>	$I_{DM}$	60	
Power Dissipation <sup>C</sup>	$P_D$	3	W
$T_A=70^\circ C$	$P_D$	2.1	
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C

#### Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient <sup>A</sup>	$R_{\theta JA}$	31	40	°C/W
Steady-State		59	75	°C/W
Maximum Junction-to-Lead <sup>C</sup>	$R_{\theta JL}$	16	24	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	30			V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=24\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			1	$\mu\text{A}$
					5	
$I_{\text{GSS}}$	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm 12\text{V}$			100	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.7	1	1.4	V
$I_{\text{D(ON)}}$	On state drain current	$V_{GS}=4.5\text{V}, V_{DS}=5\text{V}$	40			A
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=8.5\text{A}$ $T_J=125^\circ\text{C}$		20.5	24	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_D=8.5\text{A}$		30	36	
		$V_{GS}=2.5\text{V}, I_D=5\text{A}$		25	30	
$g_{\text{FS}}$	Forward Transconductance	$V_{DS}=5\text{V}, I_D=5\text{A}$	10	16		S
$V_{\text{SD}}$	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$		0.71	1	V
$I_S$	Maximum Body-Diode Continuous Current				4.3	A
<b>DYNAMIC PARAMETERS</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=15\text{V}, f=1\text{MHz}$		857		pF
$C_{\text{oss}}$	Output Capacitance			97		pF
$C_{\text{rss}}$	Reverse Transfer Capacitance			71		pF
$R_g$	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		1.4		$\Omega$
<b>SWITCHING PARAMETERS</b>						
$Q_g$	Total Gate Charge	$V_{GS}=4.5\text{V}, V_{DS}=15\text{V}, I_D=8.5\text{A}$		9.7		nC
$Q_{\text{gs}}$	Gate Source Charge			1.63		nC
$Q_{\text{gd}}$	Gate Drain Charge			3.1		nC
$t_{\text{D(on)}}$	Turn-On Delay Time	$V_{GS}=10\text{V}, V_{DS}=15\text{V}, R_L=1.8\Omega,$ $R_{\text{GEN}}=6\Omega$		14		ns
$t_r$	Turn-On Rise Time			4		ns
$t_{\text{D(off)}}$	Turn-Off Delay Time			33		ns
$t_f$	Turn-Off Fall Time			5		ns
$t_{\text{rr}}$	Body Diode Reverse Recovery Time	$I_F=5\text{A}, dI/dt=100\text{A}/\mu\text{s}$		15		ns
$Q_{\text{rr}}$	Body Diode Reverse Recovery Charge	$I_F=5\text{A}, dI/dt=100\text{A}/\mu\text{s}$		8.6		nC

A: The value of  $R_{\text{0JA}}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The value in any given application depends on the user's specific board design. The current rating is based on the  $t \leq 10\text{s}$  thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The  $R_{\text{0JA}}$  is the sum of the thermal impedance from junction to lead  $R_{\text{0JL}}$  and lead to ambient.

D. The static characteristics in Figures 1 to 6 are obtained using 80 $\mu\text{s}$  pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The SOA curve provides a single pulse rating.

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

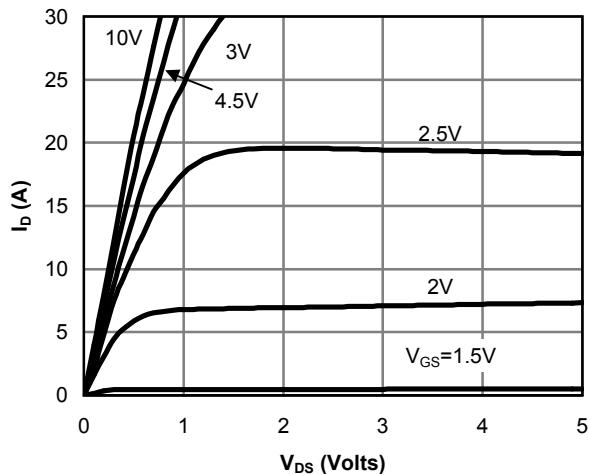


Fig 1: On-Region Characteristics

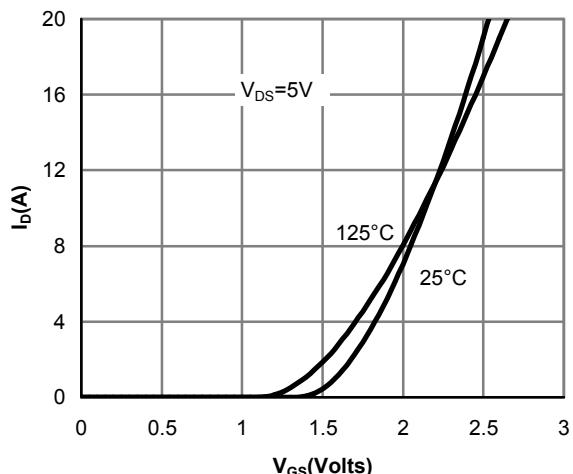


Figure 2: Transfer Characteristics

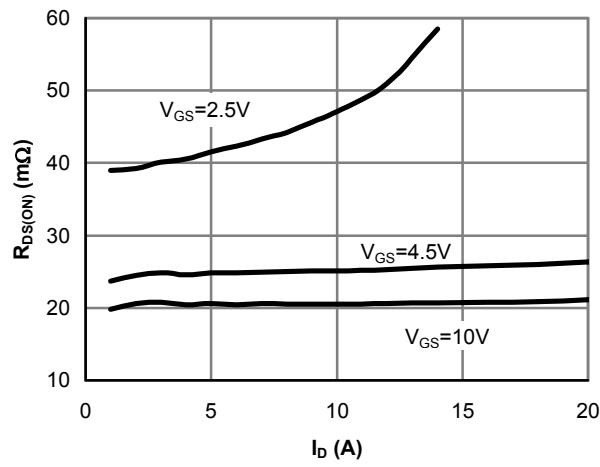


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

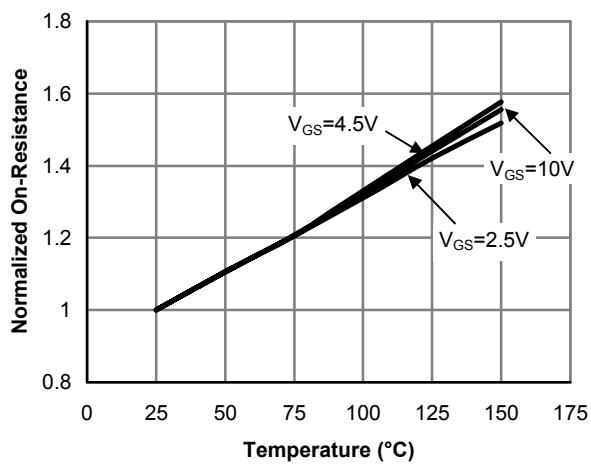


Figure 4: On-Resistance vs. Junction Temperature

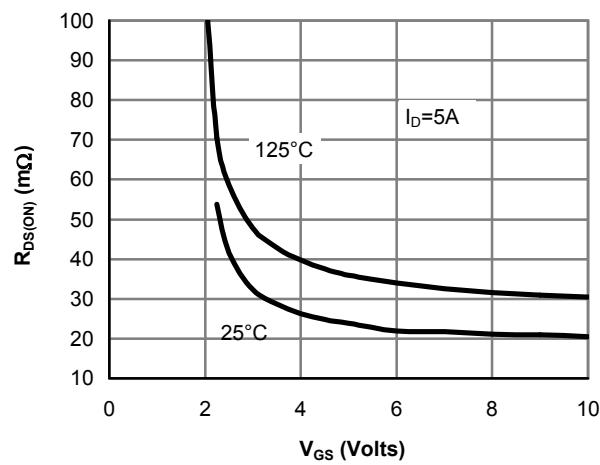


Figure 5: On-Resistance vs. Gate-Source Voltage

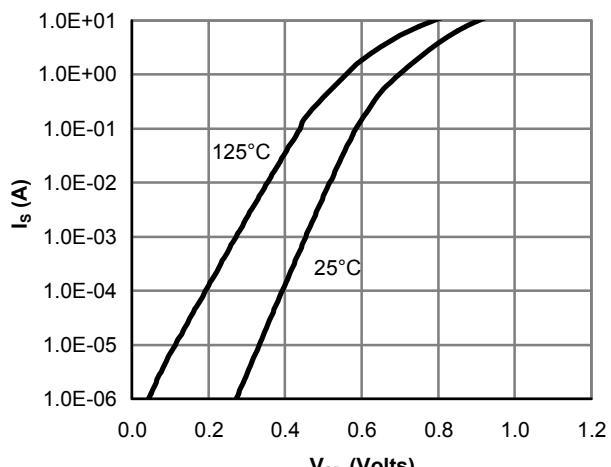


Figure 6: Body-Diode Characteristics

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

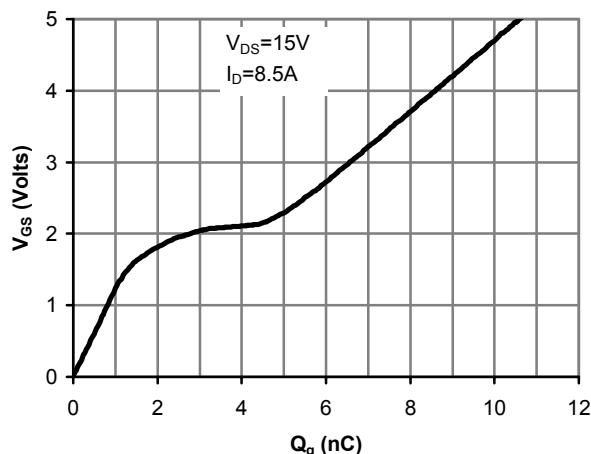


Figure 7: Gate-Charge Characteristics

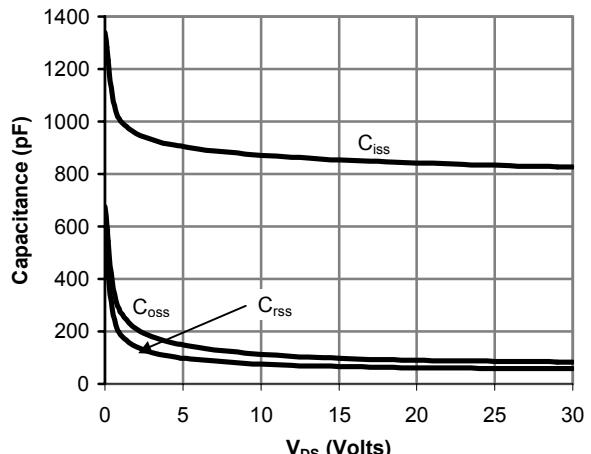


Figure 8: Capacitance Characteristics

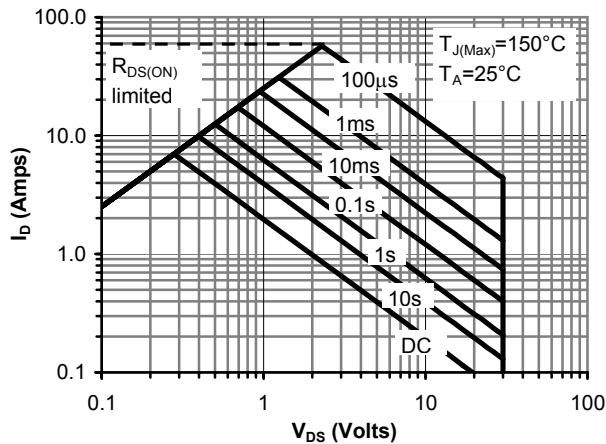


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

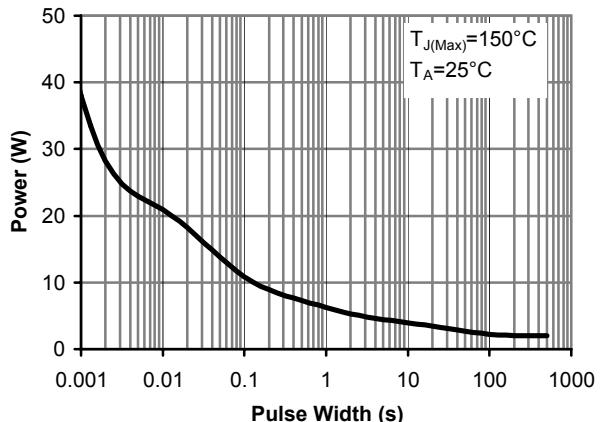


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

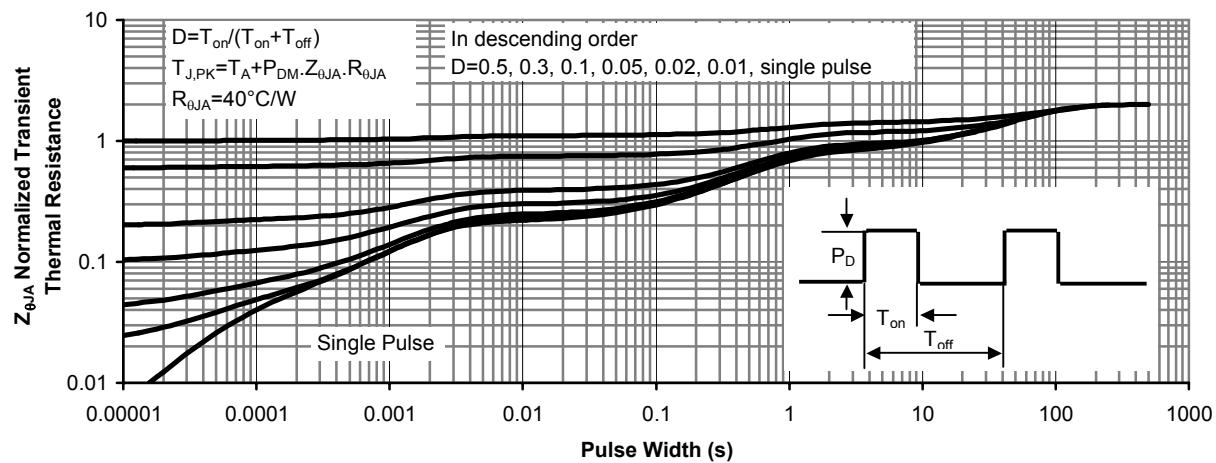
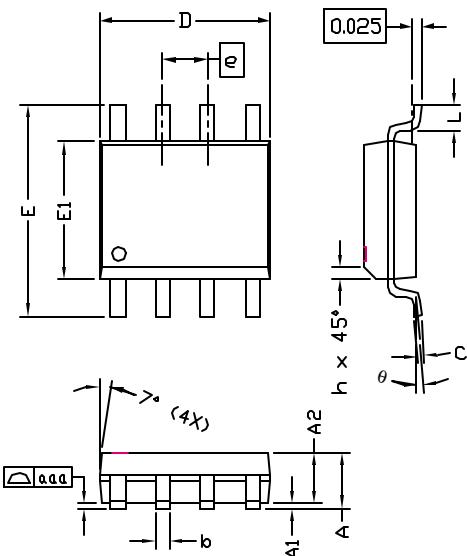


Figure 11: Normalized Maximum Transient Thermal Impedance



**ALPHA & OMEGA**  
SEMICONDUCTOR, INC.

## SO-8 Package Data



SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.45	1.50	1.55	0.057	0.059	0.061
A1	0.00	—	0.10	0.000	—	0.004
A2	—	1.45	—	—	0.057	—
b	0.33	—	0.51	0.013	—	0.020
c	0.19	—	0.25	0.007	—	0.010
D	4.80	—	5.00	0.189	—	0.197
E1	3.80	—	4.00	0.150	—	0.157
e	1.27 BSC			0.050 BSC		
E	5.80	—	6.20	0.228	—	0.244
h	0.25	—	0.50	0.010	—	0.020
L	0.40	—	1.27	0.016	—	0.050
aaa	—	—	0.10	—	—	0.004
θ	0°	—	8°	0°	—	8°

NOTE:

1. LEAD FINISH: 150 MICROINCHES (3.8  $\mu$ m) MIN.  
THICKNESS OF Tin/Lead (SOLDER) PLATED ON LEAD
2. TOLERANCE  $\pm 0.100$  mm (4 mil) UNLESS OTHERWISE SPECIFIED
3. COPLANARITY : 0.1000 mm
4. DIMENSION L IS MEASURED IN GAGE PLANE

### PACKAGE MARKING DESCRIPTION

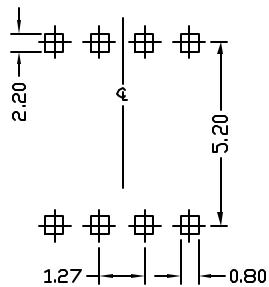


NOTE:  
 LG - AOS LOGO  
 PARTN - PART NUMBER CODE.  
 F - FAB LOCATION  
 A - ASSEMBLY LOCATION  
 Y - YEAR CODE  
 W - WEEK CODE.  
 LN - ASSEMBLY LOT CODE

### SO-8 PART NO. CODE

PART NO.	CODE	PART NO.	CODE	PART NO.	CODE
AO4400	4400	AO4800	4800	AO4700	4700
AO4401	4401	AO4801	4801	AO4701	4701

### RECOMMENDED LAND PATTERN



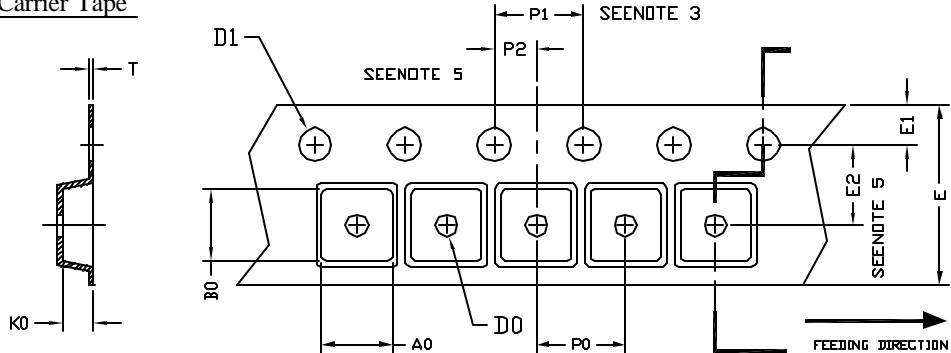
UNIT: mm



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**SO-8 Tape and Reel Data**

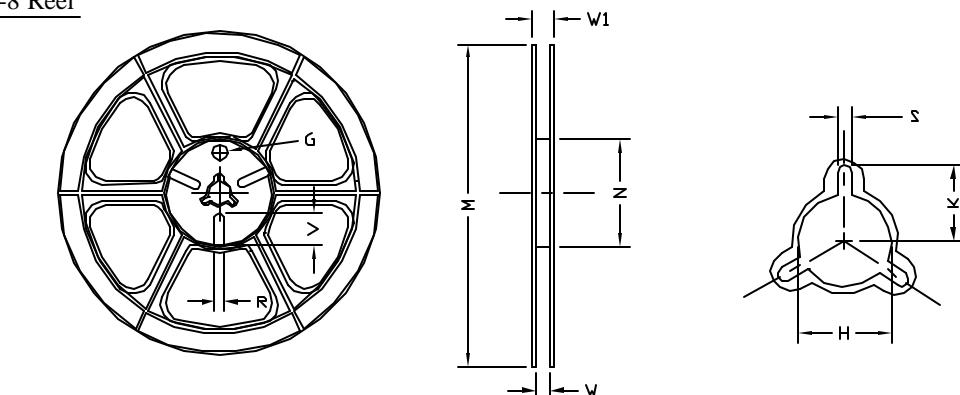
SO-8 Carrier Tape



UNIT: MM

PACKAGE	A0	B0	K0	D0	D1	E	E1	E2	P0	P1	P2	T
SO-8 (12 mm)	6.40 $\pm 0.10$	5.20 $\pm 0.10$	2.10 $\pm 0.10$	16.0 $\pm 0.10$	1.50 $\pm 0.10$	12.00 $\pm 0.30$	1.75 $\pm 0.10$	5.50 $\pm 0.05$	8.00 $\pm 0.10$	4.00 $\pm 0.10$	2.00 $\pm 0.05$	0.25 $\pm 0.05$

SO-8 Reel



UNIT: MM

TAPE SIZE	REEL SIZE	M	N	W	W1	H	K	S	G	R	V
12 mm	$\phi 330$	$\phi 330.00$ $\pm 0.50$	$\phi 97.00$ $\pm 0.10$	13.00 $\pm 0.30$	17.40 $\pm 1.00$	$\phi 13.00$ $+0.50$ $-0.20$	10.60	2.00 $\pm 0.50$	---	---	---

SO-8 Tape

Leader / Trailer  
& Orientation

